

C3
12. (Amended) The method as recited in claim 9, further comprising:
plugging a stub that supports the printed circuit board of the installed IC package into a
substrate of the tray.

D1
C4
13. (Twice Amended) A method for decapsulating installed integrated circuit (IC)
packages, comprising:
receiving an IC package permanently installed onto a first surface of a printed circuit board
(PCB) wherein the printed circuit board includes a second surface located below the first surface of
the printed circuit board;

spraying a decapsulation fluid onto the installed IC package via an injection head clamped to
the installed IC package, the injection head having a nozzle disposed above the installed IC package
that is in fluid communication with an inlet port of said injection head, and a return port that is in
fluid communication with an outlet port of the injection head.

14. (Amended) The method as recited in claim 13, further comprising:
controlling a flow of the decapsulation fluid through a pair of tubes that couple an extender
to the injection head using a corresponding pair of valves.

C5
15. (Amended) The method as recited in claim 13, further comprising:
plugging a stub that supports the PCB of the installed IC package into a substrate.

16. (Amended) The method as recited in Claim 13 further comprising:
forming a seal between injection head and the installed IC package to prevent decapsulation
fluid from contacting the PCB of the installed IC package.